

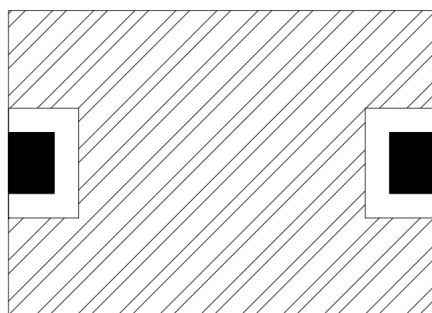
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

NO.	Parameter	Frequency (MHz)	SPC		
			Min.	Typ.	Max.
1	Insertion Loss (dB)	940~1230			1.8
2	Ripple (dB)	940~1230			1.0
3	VSWR	940~1230			1.8
4	Attenuation (dBC)	DC~750	40		
		1380~2000	40		
5	In/Output Impedance (Ω)		50		
6	Power		5W		
Operating & Storage Condition (Component) Operation Temperature Range: -55℃ ~ +85℃ Storage Temperature Range: -55℃~ +85℃					
Storage Condition before Soldering (Included packaging material) Storage Temperature Range: +5 ~ +40 ℃ Humidity: 30 to 70% relative humidity					

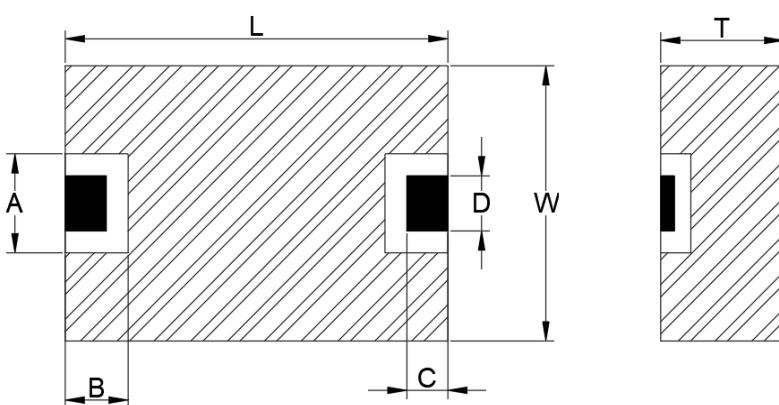
Construction



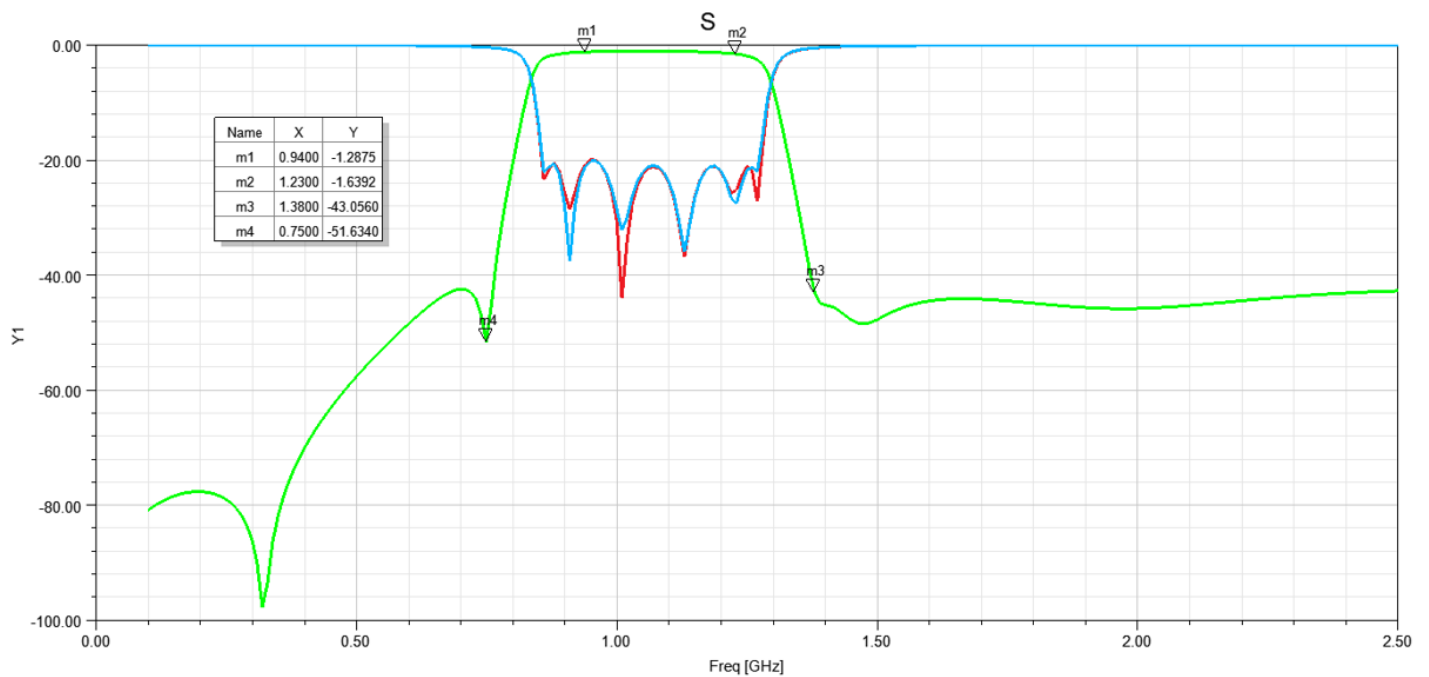
 I/O Port

 GND

Dimensions

Figure	Symbol	Dimension (mm)
	L	14.00±0.20
	W	10.00±0.20
	T	4.50 MAX
	A	3.60±0.10
	B	2.30±0.10
	C	1.50±0.10
	D	2.00±0.10

Typical Electrical Characteristics (T=25°C)



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For detailed performance specs & shopping online see Yantel web site : www.yantel-corp.com

Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.